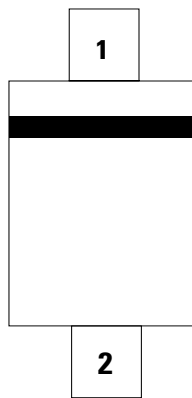


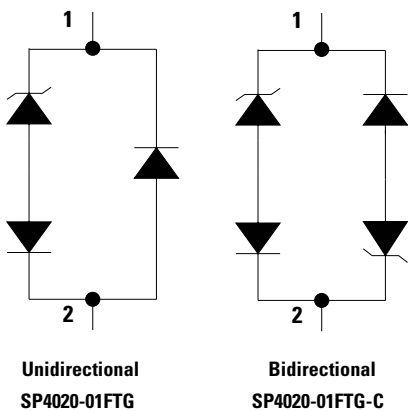
# SP4020 Series 2.5pF, 30A Discrete TVS Diode



## Pinout



## Functional Block Diagram



## Description

The SP4020 components integrate low capacitance steering diodes with one or two avalanche breakdown diodes for unidirectional or bidirectional protection, respectively, to protect against ESD and lightning induced surge events. These devices can safely absorb up to 30A per IEC 61000-4-5, 2nd Edition ( $t_p=8/20\mu s$ ) without performance degradation and a minimum  $\pm 30kV$  ESD per IEC 61000-4-2 International Standard. The low loading capacitance and high surge capability make it ideal for protecting telecommunication ports such as Ethernet and other high speed data interfaces.

## Features

- ESD, IEC 61000-4-2,  $\pm 30kV$  contact,  $\pm 30kV$  air
- EFT, IEC 61000-4-4, 40A (5/50ns)
- Lightning, 30A (8/20 as defined in IEC 61000-4-5 2<sup>nd</sup> edition)
- Low capacitance of 2.5pF (@  $V_R=0V$ )
- Low leakage current of 0.1 $\mu A$  at 3.3V
- Unidirectional and Bidirectional configuration
- Small SOD323 package fits 0805 footprints
- Moisture Sensitivity Level (MSL-1)
- AEC-Q101 Qualified
- Halogen-Free, Lead-Free and RoHS-Compliant

## Applications

- 10/100/1000 Ethernet
- T1/E1/T3/E3
- USB 1.1/2.0
- USB 3.0/3.1
- Power Ports
- Computers and Peripherals
- Instrumentation
- Medical Equipment

## Additional Information



Life Support Note:

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	30	A
$P_{PK}$	Peak Pulse Power ( $t_p=8/20\mu s$ )	750	W
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

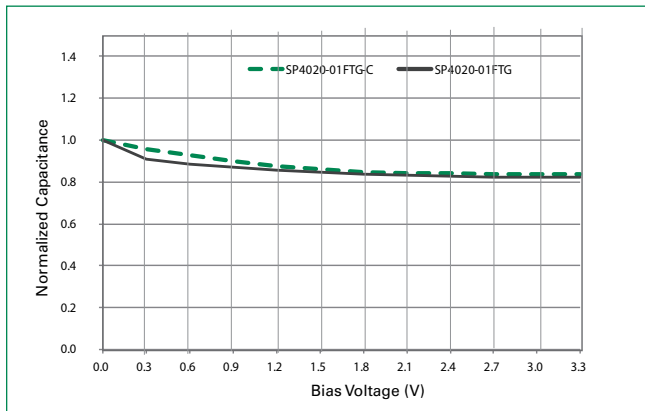
### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Breakdown Voltage	$V_{BR}$	$I_R=2\mu A$	3.5			V
Reverse Standoff Voltage	$V_{RWM}$	$I_R=1\mu A$			3.3	V
Reverse Leakage Current	$I_{LEAK}$	$V_R=3.3V$		0.1	0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		6.6		V
		$I_{PP}=10A, t_p=8/20\mu s, Fwd$		14.2		V
		$I_{PP}=24A, t_p=8/20\mu s, Fwd$		21.8		V
Dynamic Resistance <sup>2</sup>	$R_{DYN}$	TLP, $t_p=100ns, I/O$ to GND		0.40		$\Omega$
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact Discharge)	$\pm 30$			kV
		IEC 61000-4-2 (Air Discharge)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V, $f=1MHz$		2.5		pF

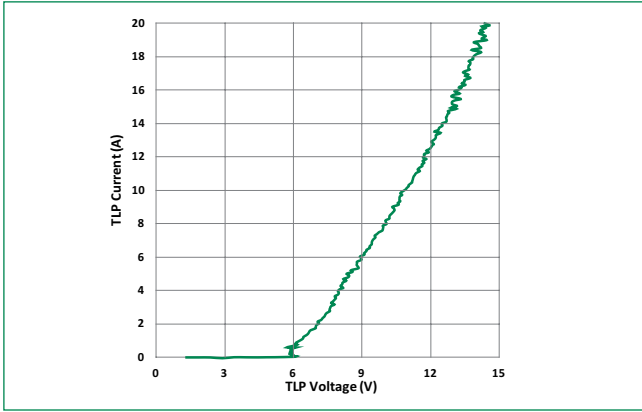
**Note:**

- Parameter is guaranteed by design and/or component characterization.
- Transmission Line Pulse (TLP) with 100ns width and 200ps rise time.

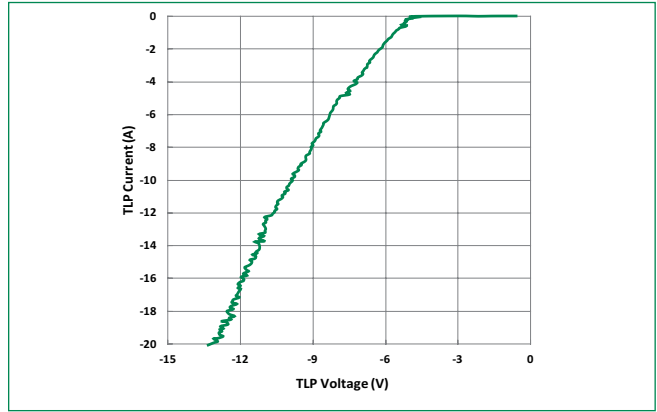
### Normalized Capacitance vs. Bias Voltage



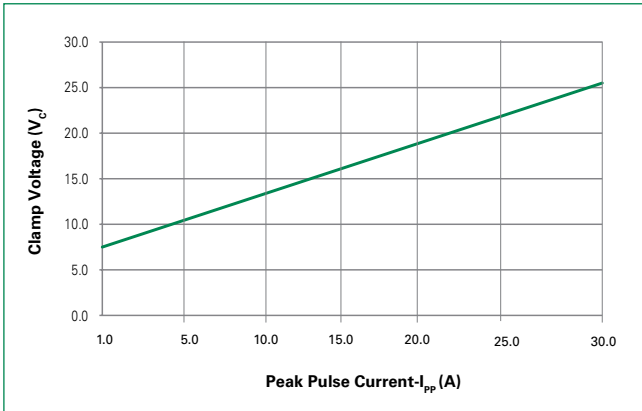
**Positive Transmission Line Pulsing (TLP) Plot**



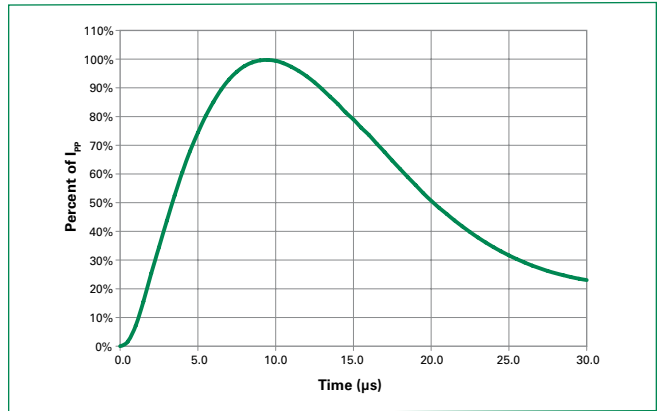
**Negative Transmission Line Pulsing (TLP) Plot**



**Clamping Voltage vs. I<sub>pp</sub>**



**8/20 Pulse Waveform**

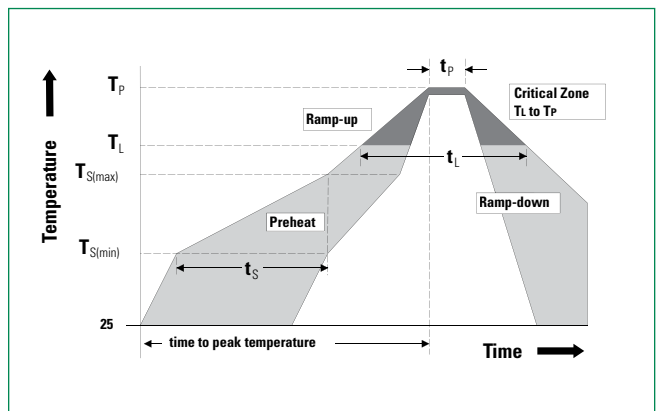


**Soldering Parameters**

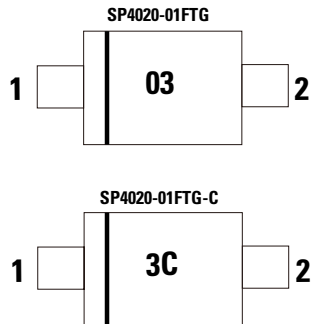
<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
<b>Average ramp up rate (Liquidus) Temp (<math>T_L</math>) to peak</b>		3°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		260°C

**Product Characteristics**

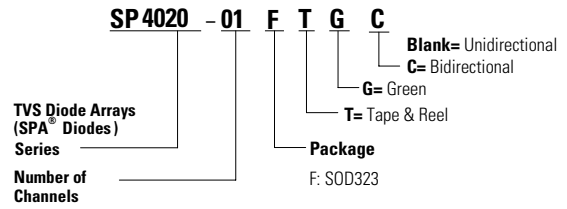
<b>Lead Plating</b>	Matte Tin
<b>Lead Material</b>	Alloy 42
<b>Lead Coplanarity</b>	0.0004 inches (0.102mm)
<b>Substrate Material</b>	Silicon
<b>Body Material</b>	Molded Compound
<b>Flammability</b>	UL Recognized compound meeting flammability rating V-0



**Part Marking System**



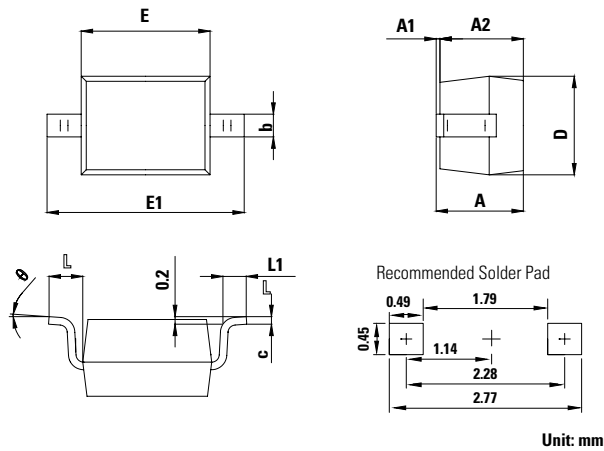
**Part Numbering System**



**Ordering Information**

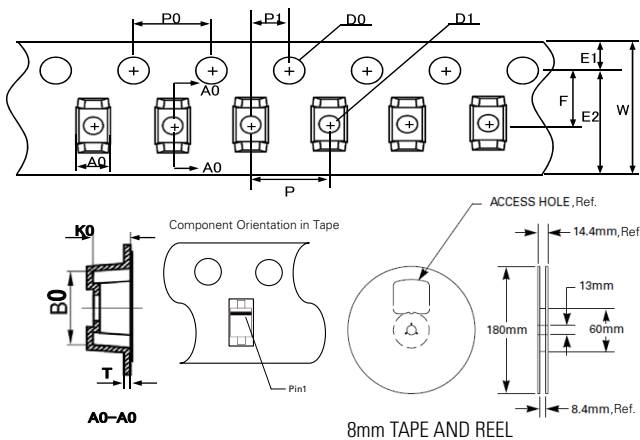
Part Number	Package	Min. Order Qty.
SP4020-01FTG	SOD323	3000
SP4020-01FTG-C	SOD323	3000

**Package Dimensions -SOD323**



Symbol	SOD323			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.8	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A2	0.80	0.90	0.031	0.035
b	0.25	0.35	0.010	0.014
c	0.08	0.15	0.003	0.006
D	1.20	1.40	0.047	0.055
E	1.60	1.80	0.063	0.071
E1	2.50	2.75	0.098	0.108
L1	0.22	0.40	0.009	0.016

**Embossed Carrier Tape & Reel Specification – SOD323**



Symbol	Millimeters
A0	1.46+/-0.10
B0	2.90+/-0.10
W	8.0+0.3/-0.10
D0	1.50+0.10
D1	0.45min/1.15max
E1	1.75+/-0.10
E2	-
F	3.50+/-0.10
P0	4.00+/-0.10
P	4.00+/-0.10
P1	2.00+/-0.05
K0	1.25+/-0.10
T	0.254+/-0.02

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